

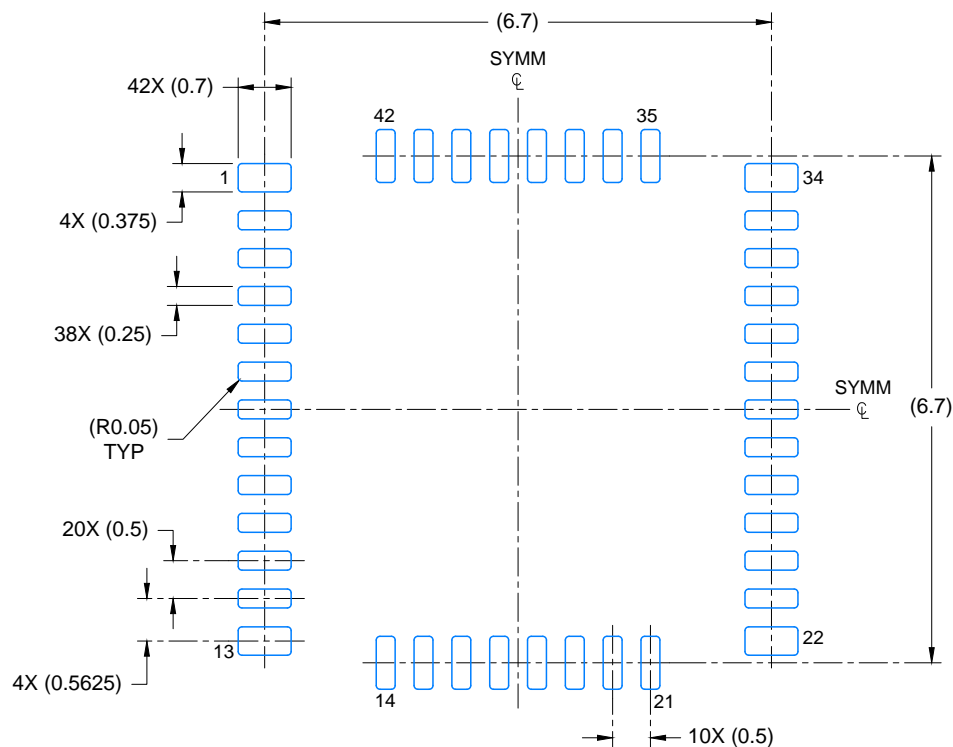
## PACKAGE OUTLINE

VQFN - 1 mm max height

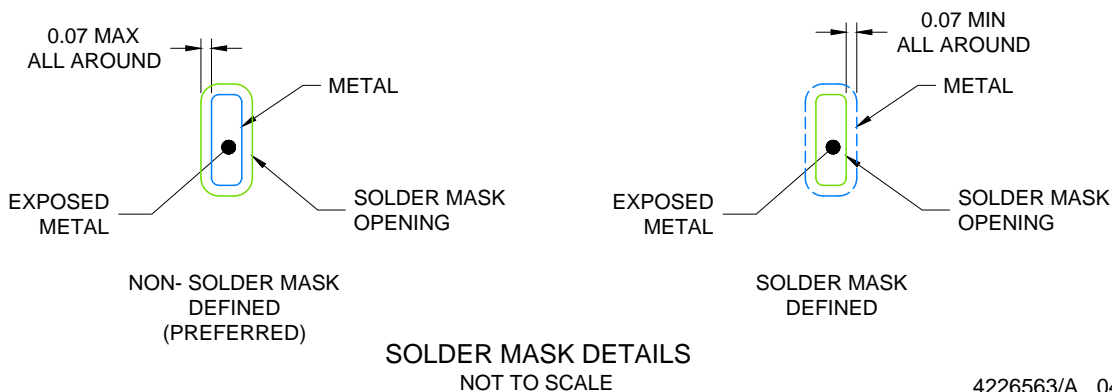
The drawing shows a 16-pin micro connector with the following dimensions and features:
 

- Overall Dimensions:** Width 7.1 (6.9), Height 7.1 (6.9).
- Internal Dimensions:** Width 3.89 (3.69), Height 3.89 (3.69).
- Pin Dimensions:** Pin 1 ID, 42, 35, 34, 42X 0.6 (0.4).
- Pin Spacing:** 2X 3.5, 14X 0.5, 4X 1.125, 2X 5, 20X 0.5, 4X 0.5625.
- Seating Plane:** 0.05 (0.00), 0.08 (C).
- Symmetry:** SYMM (Center of Symmetry).
- Callouts:** EXPOSED PAD, PIN1 ID, (0.2) TYP.
- Feature Callouts:** 0.1 (M) C A B, 0.05 (M) C, 0.35 (0.15), 0.425 (0.325).

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package incorporates an exposed thermal pad that is designed to be attached directly to an external heat sink. This optimizes the heat transfer from the integrated circuit (IC).



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS  
NOT TO SCALE

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NOTES: (continued)

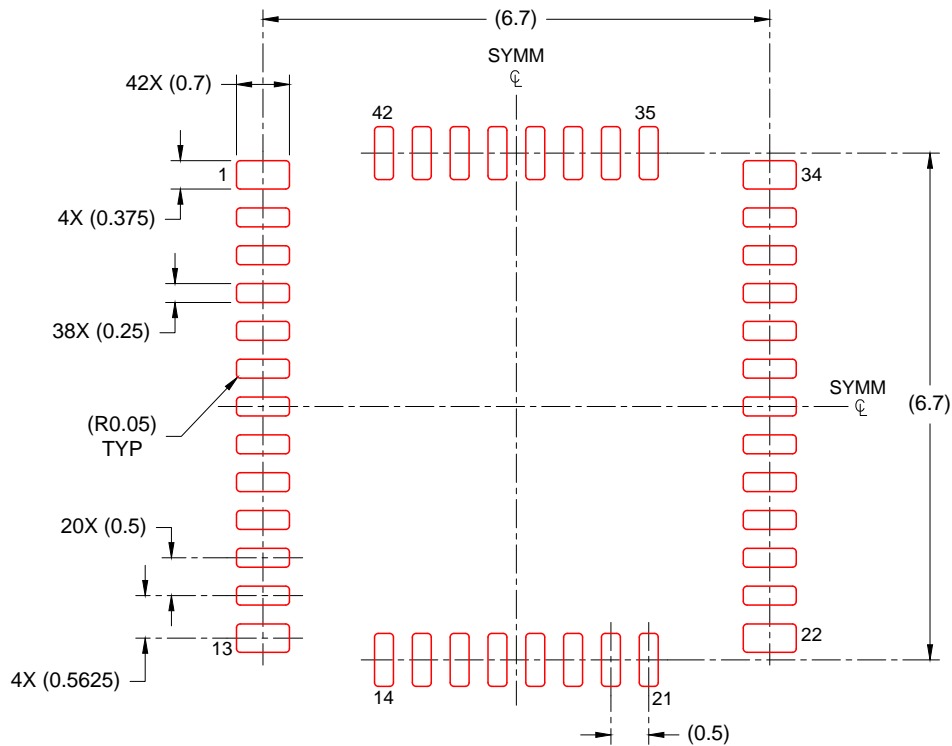
- For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)) .
- For best BLR performance please use non solder mask defined pads.

# EXAMPLE STENCIL DESIGN

REB0042A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK-NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125mm THICK STENCIL  
SCALE: 10X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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